

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4809733

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
DENNIS R. SMALLEY	09/08/2003
RECEIVING PARTY DATA	
Name:	MICROFABRICA INC.
Street Address:	7911 HASKELL AVENUE
City:	VAN NUYS
State/Country:	CALIFORNIA
Postal Code:	91406
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	8601405
CORRESPONDENCE DATA	
Fax Number:	(818)997-3659
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	8187863322 X105
Email:	dsmalley@microfabrica.com
Correspondent Name:	DENNIS R. SMALLEY
Address Line 1:	7911 HASKELL AVENUE
Address Line 4:	VAN NUYS, CALIFORNIA 91406
ATTORNEY DOCKET NUMBER:	P-US068-D-MF
NAME OF SUBMITTER:	DENNIS R. SMALLEY
SIGNATURE:	/Dennis R. Smalley/
DATE SIGNED:	02/05/2018
Total Attachments: 1	
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ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we

Dennis R. Smalley	23524 Maple St., Newhall, CA 91321
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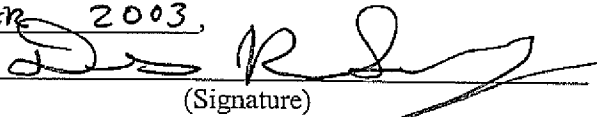
hereby sell, assign and transfer to Microfabrica Inc. having a place of business at 1103 W. Isabel Street, Burbank, California 91506, its successors, and assigns, the entire right, title, and interest throughout the world to the inventions that we have contributed to individually or jointly (whether or not claimed) as set forth in the following patents and/or patent applications

Country	Patent or App. No.	Issue Date or Filing Date	Title
US	App. No. 10/434,519	Filed May 7, 2003	Methods of and Apparatus for Electrochemically Fabricating Structures Via Interlaced Layers or Via Selective Etching and Filling of Voids
WIPO	App. No. PCT/US03/14860	Filed May 7, 2003	Methods of and Apparatus for Electrochemically Fabricating Structures Via Interlaced Layers or Via Selective Etching and Filling of Voids

and for all other patent applications and patents of every country for said inventions (whether or not yet filed), including divisions, reissues, continuations, and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for other patents in the United States and/or foreign countries for said inventions, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with these patent applications and/or patents, and generally to do everything possible to aid said assignee, their successors, assigns, and nominees, at their request and expense, in obtaining and enforcing patents for said inventions in all countries; and we request that the United States Patent and Trademark Office and all other patent granting authorities to issue all patents granted for said inventions to the above-named assignee, its successors, and assigns.

First assignor

Executed this 8TH day of SEPTEMBER, 2003.

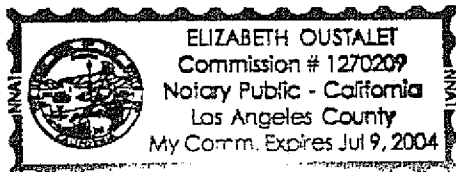

 (Signature)

Dennis R. Smalley
 Name (Typed or Printed)

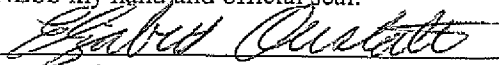
State of California)

County of Los Angeles) ss.

On 9/8/03 before me, Elizabeth Oustalet personally appeared Dennis R. Smalley personally known to me or proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is(are) subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.



WITNESS my hand and official seal.


 SIGNATURE OF NOTARY